

PTN3332

High speed differential line receiver

Rev. 01 — 07 January 2004

Product data

1. Description

The PTN3332 is a differential line receiver that implements the electrical characteristics of Low-Voltage Differential Signaling (LVDS). This device meets or exceeds the requirements of the ANSI *TIA/EIA-644 Standard*. LVDS is used to achieve higher data rates on commonly used media. LVDS overcomes the limitations of achievable slew rates and EMI restrictions of previous differential signaling techniques. The PTN3332 operates at a 3.3 volt supply level. Any of the four differential receivers provides a valid logical output state with a ± 100 mV differential input voltage within the input common-mode voltage range. The input common-mode voltage range allows 1 volt of ground potential difference between two LVDS nodes.

The intended application of this device is for point-to-point baseband transmission rates over a controlled impedance media of approximately 100 Ω . The maximum rates and distance of data transfer are dependent upon the attenuation characteristics of the media selected and the noise coupling to the environment.

The PTN3332 is designed to function over the full industrial temperature range of -40 °C to $+85$ °C.

2. Features

- Meets or exceeds the requirements of ANSI *TIA/EIA-644 Standard*
- Designed for signaling rates of up to 400 Mbps
- Differential input thresholds of ± 100 mV
- Power dissipation of 60 mW typical at 200 MHz
- Typical propagation delay of 2.6 ns
- Low Voltage TTL (LVTTTL) logic output levels
- Pin compatible with AM26LS32 and SN65LVDS32
- Open-circuit fail safe.

3. Applications

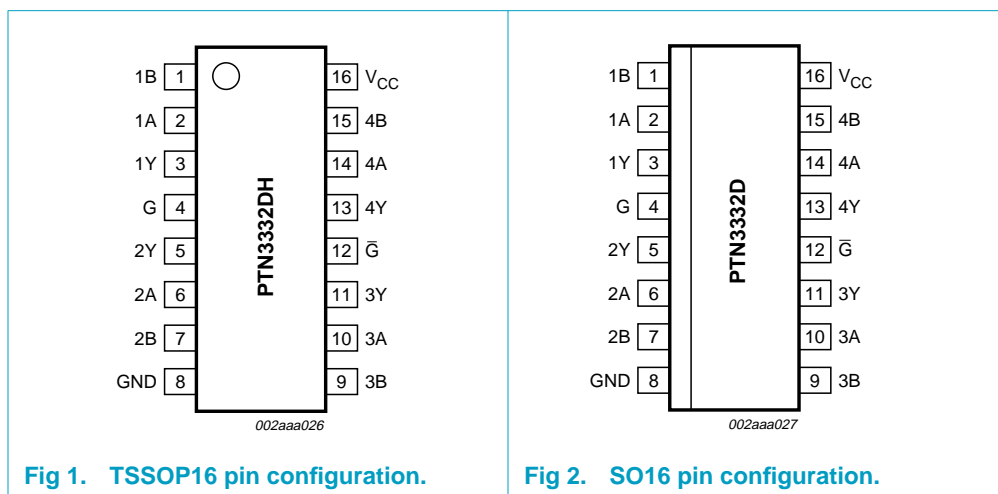
- Low voltage, low EMI, high speed differential signal receiver
- Point-to-point high speed data transmission
- High performance switches and routers.



PHILIPS

4. Pinning information

4.1 Pinning



4.2 Pin description

Table 1: Pin description

Symbol	Pin	Description
1B	1	LVDS inverting input
1A	2	LVDS non-inverting input
1Y	3	LVTTL output
G	4	Enable (active-HIGH)
2Y	5	LVTTL output
2A	6	LVDS non-inverting input
2B	7	LVDS inverting input
GND	8	Ground
3B	9	LVDS inverting input
3A	10	LVDS non-inverting input
3Y	11	LVTTL output
\bar{G}	12	Enable (active-LOW)
4Y	13	LVTTL output
4A	14	LVDS non-inverting input
4B	15	LVDS inverting input
V _{CC}	16	Supply

5. Ordering information

Table 2: Ordering information

Type number	Package		Version
	Name	Description	
PTN3332DH	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
PTN3332D	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

6. Functional diagram division

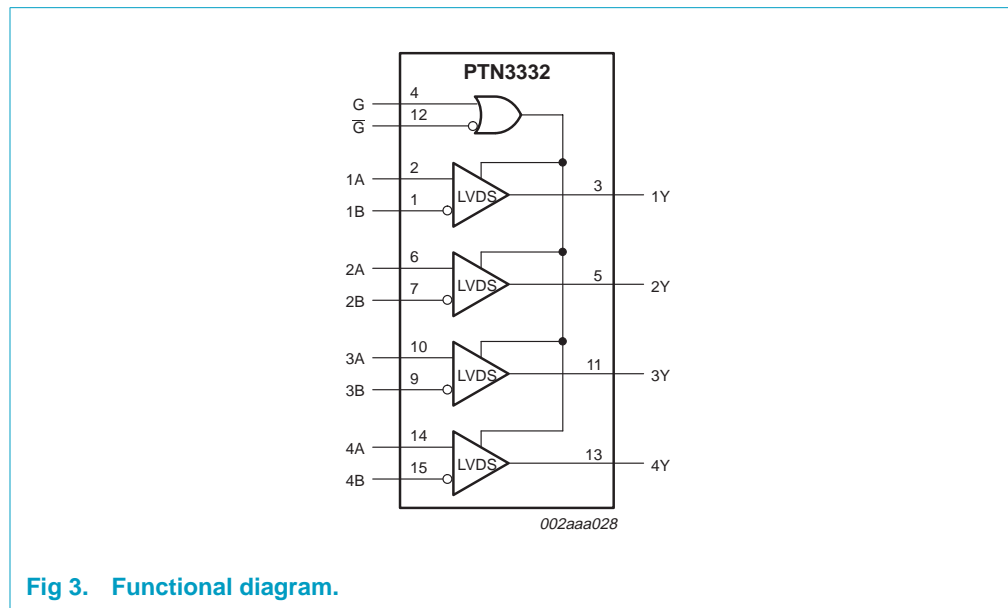


Fig 3. Functional diagram.

7. Functional description

7.1 Function table

Table 3: Function table division

Differential input A, B	Enables		Output Y
	G	Ḡ	
$V_{ID} \geq 100 \text{ mV}$	H	X	H
	X	L	H
$-100 \text{ mV} < V_{ID} < 100 \text{ mV}$	H	X	?
	X	L	?
$V_{ID} \leq -100 \text{ mV}$	H	X	L
	X	L	L
X	L	H	Z
Open	H	X	L
	X	L	L

[1] H = HIGH level; L = LOW level; X = irrelevant; Z = high impedance; ? = indeterminate state.

8. Limiting values

Table 4: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Min	Max	Unit
V_{CC}	supply voltage	-0.5	4.0	V
V_I	input voltage (enables and outputs)	-0.5	$V_{CC} + 0.5$	V
	input voltage (A or B inputs)	-0.5	4.0	V
T_{amb}	operating ambient temperature range	-40	+85	°C
T_j	operating junction temperature	-40	+150	°C
T_{stg}	storage temperature range	-65	+150	°C
	ESD	>2	-	kV

- [1] Values beyond absolute maximum ratings can cause the device to be prematurely damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

9. Recommended operating conditions

Table 5: Recommended operating conditions

Symbol	Parameter	Min	Nom	Max	Unit
V_{CC}	supply voltage	3	3.3	3.6	V
V_{IH}	HIGH-level input voltage	2	-	-	V
V_{IL}	LOW-level input voltage	-	-	0.8	V
V_{ID}	Magnitude of differential input voltage	0.1	-	0.6	V
V_{IC}	Common-mode input voltage	$V_{ID}/2$	-	$2.4 - V_{ID}/2$	V
T_{amb}	Operating temperature range	-40	-	+85	°C

10. Static characteristics

Table 6: DC electrical characteristics

Over recommended operating conditions, unless otherwise noted.

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
V_{rr+}	positive differential input voltage threshold	See Figure 4 and Table 8.	–	–	100	mV
V_{rr-}	negative differential input voltage threshold		–100	–	–	mV
V_{OH}	HIGH-level output voltage	$I_{OH} = -8$ mA	2.4	–	–	V
		$I_{OH} = -4$ mA	2.8	–	–	V
V_{OL}	LOW-level output voltage	$I_{OL} = 8$ mA	–	–	0.4	V
I_{CC}	supply current	enabled, no load	–	10	18	mA
		disabled	–	0.25	0.5	mA
I_I	input current (A or B inputs)	$V_I = 0$ V	–2	–10	–20	μ A
		$V_I = 2.4$ V	–1.2	–3	–	μ A
$I_{I(OFF)}$	Power-off input current (A or B inputs)	$V_{CC} = 0$ V; $V_I = 3.6$ V	–	6	20	μ A
I_{IH}	HIGH-level input current (G or \overline{G} inputs)	$V_{IH} = 2$ V	–	–	10	μ A
I_{IL}	LOW-level input current (G or \overline{G} inputs)	$V_{IL} = 0.8$ V	–	–	10	μ A
I_{OZ}	High-impedance output current	$V_O = 0$ V or V_{CC}	–10	–	10	μ A

[1] All typical values are at $T_{amb} = 25$ °C and $V_{CC} = 3.3$ V.

11. Dynamic characteristics

Table 7: AC electrical characteristics

Over recommended operating conditions, unless otherwise noted.

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
t_{PLH}	propagation delay, LOW-to-HIGH level output	$C_L = 10$ pF	1.3	2.6	6	ns
t_{PHL}	propagation delay, HIGH-to-LOW level output	See Figure 5.	1.3	2.5	6	ns
t_r	output rise time (20 to 80%)		–	0.6	–	ns
t_f	output fall time (80 to 20%)		–	0.7	–	ns
$t_{sk(p)}$	pulse skew ($t_{PHL} - t_{PLH}$)		–	–	0.4	ns
$t_{sk(o)}$	channel-to-channel output skew		[2]	0.1	0.3	ns
$t_{sk(p-p)}$	part-to-part skew		[3]	–	1	ns
t_{PZH}	propagation delay, high-impedance to HIGH-level output	See Figure 6.	–	8	12	ns
t_{PZL}	propagation delay, high-impedance to LOW-level output		–	3	12	ns
t_{PHZ}	propagation delay, HIGH-level to high-impedance output		–	6.5	12	ns
t_{PLZ}	propagation delay, LOW-level to high-impedance output		–	5.5	12	ns

[1] All typical values are at $T_{amb} = 25$ °C, and $V_{CC} = 3.3$ V.

[2] $t_{sk(o)}$ is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

[3] $t_{sk(p-p)}$ is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, same temperature, and have identical packages and test circuits.

12. Test figures

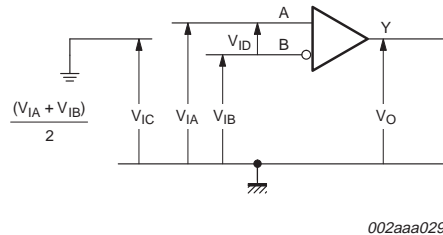


Fig 4. Voltage definitions.

Table 8: Receiver minimum and maximum input threshold test voltages

Applied voltages		Resulting differential input voltage	Resulting common-mode input voltage
V_{IA}	V_{IB}	V_{ID}	V_{IC}
1.25 V	1.15 V	100 mV	1.2 V
1.15 V	1.25 V	-100 mV	1.2 V
2.4 V	2.3 V	100 mV	2.35 V
2.3 V	2.4 V	-100 mV	2.35 V
0.1 V	0 V	100 mV	0.05 V
0 V	0.1 V	-100 mV	0.05 V
1.5 V	0.9 V	600 mV	1.2 V
0.9 V	1.5 V	-600 mV	1.2 V
2.4 V	1.8 V	600 mV	2.1 V
1.8 V	2.4 V	-600 mV	2.1 V
0.6 V	0 V	600 mV	0.3 V
0 V	0.6 V	-600 mV	0.3 V

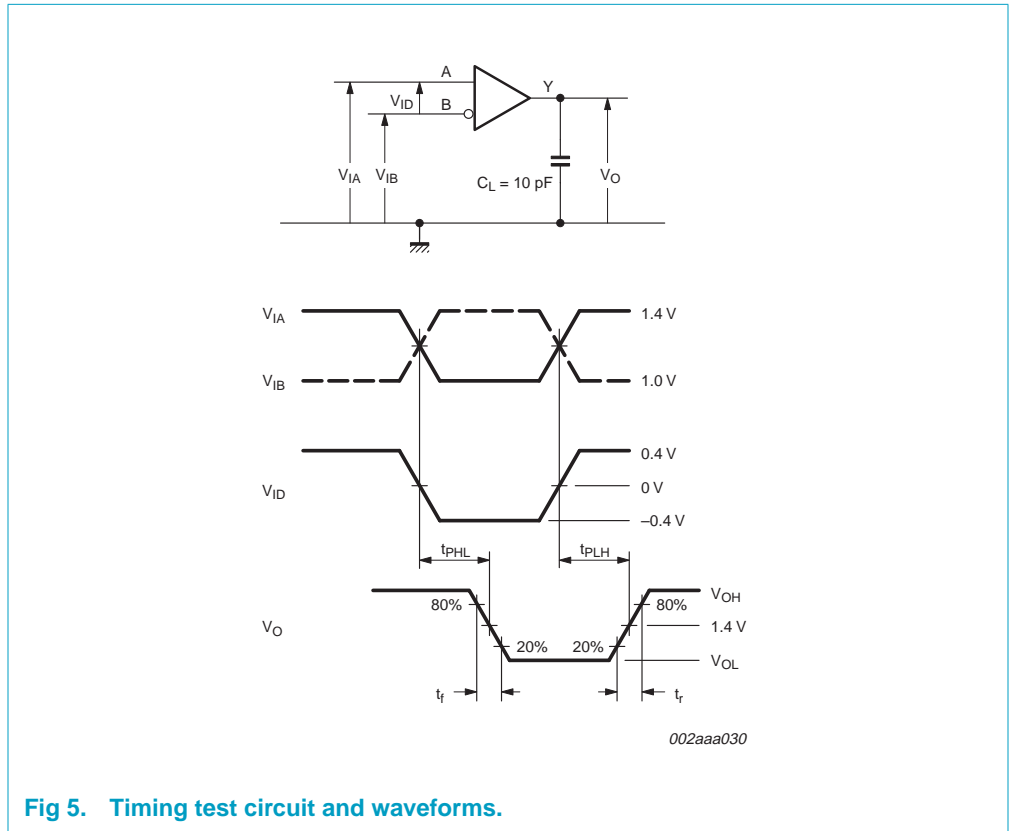


Fig 5. Timing test circuit and waveforms.

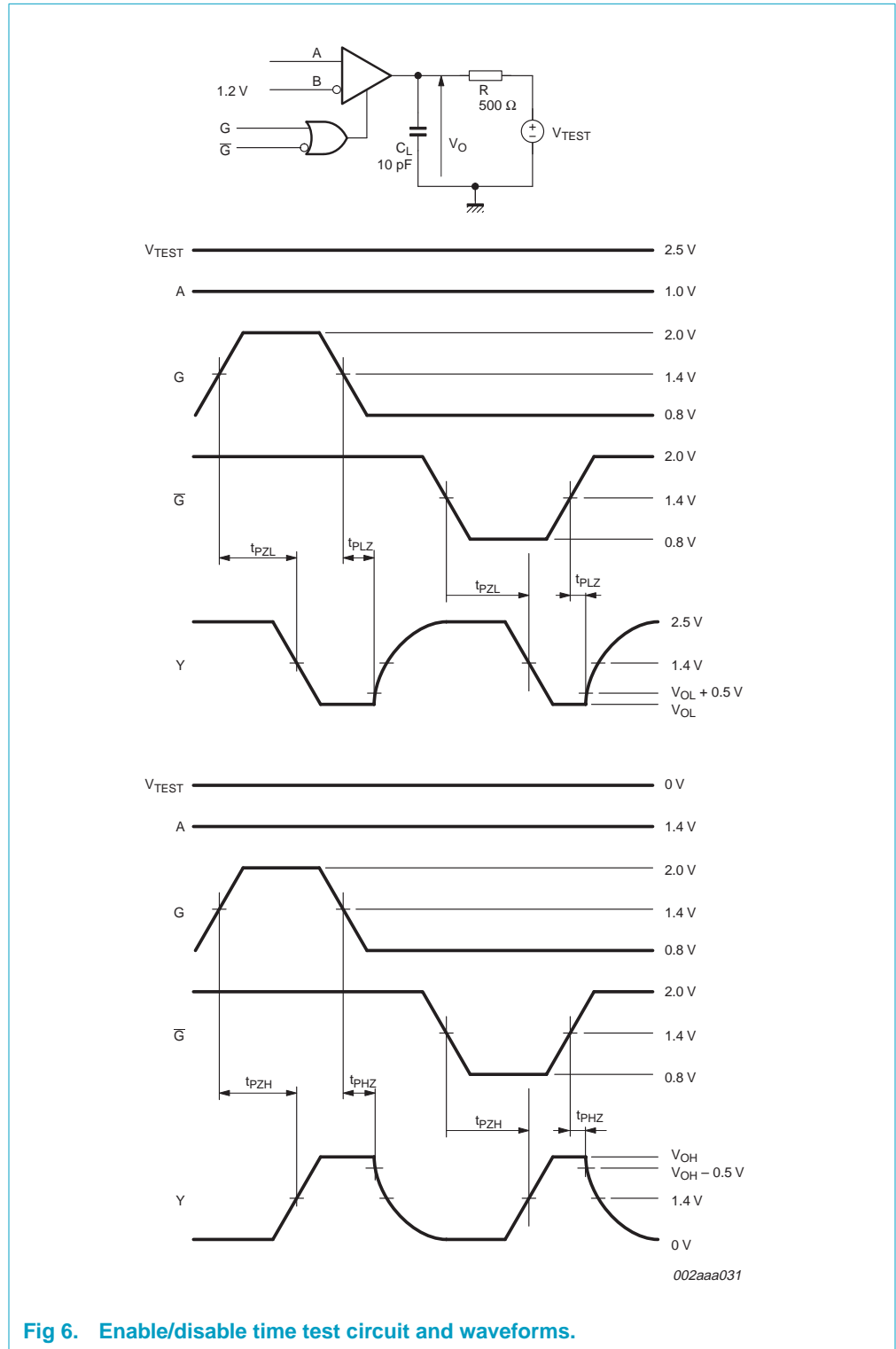


Fig 6. Enable/disable time test circuit and waveforms.

13. Package outline

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

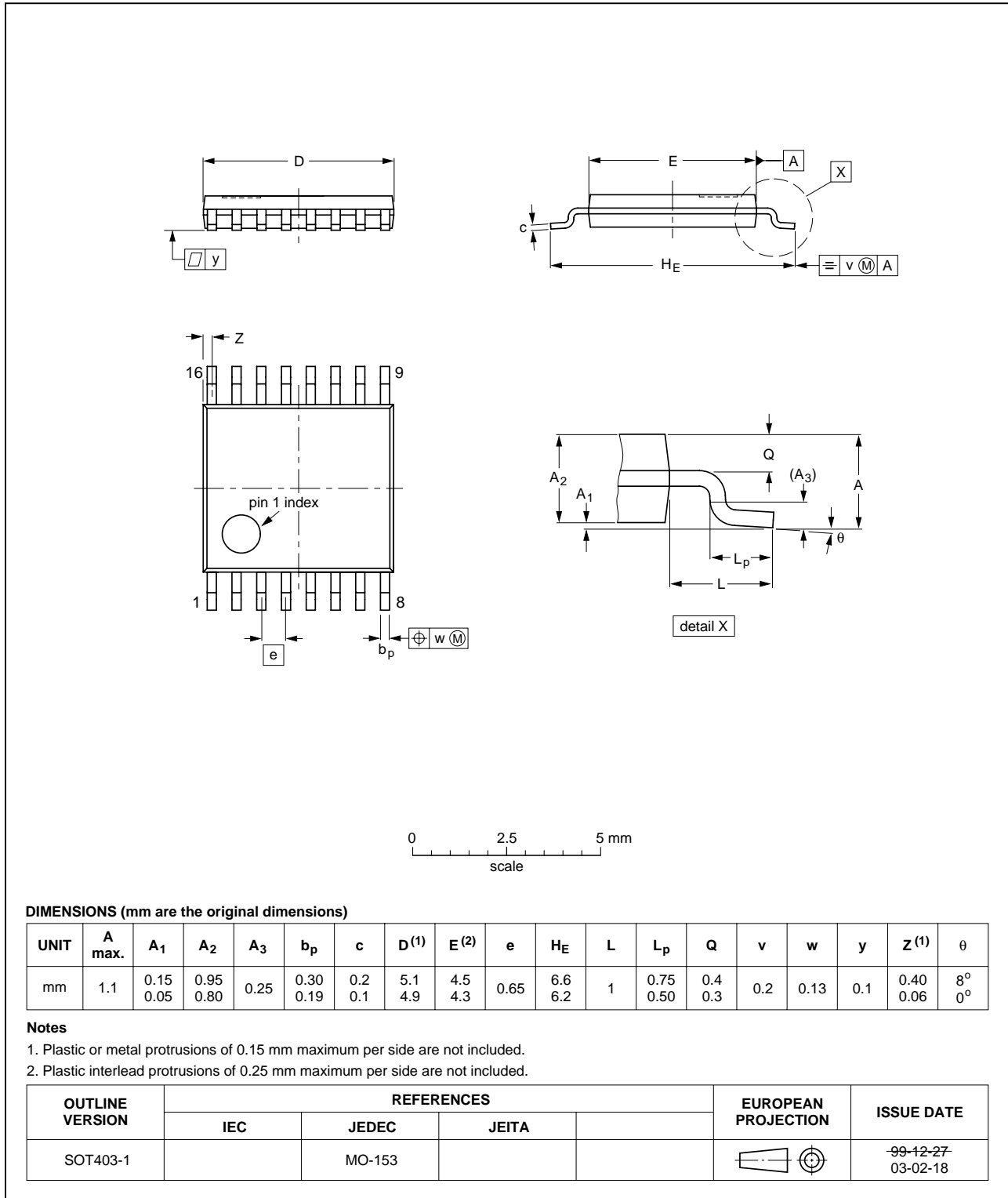


Fig 7. TSSOP16 package outline (SOT403-1).

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

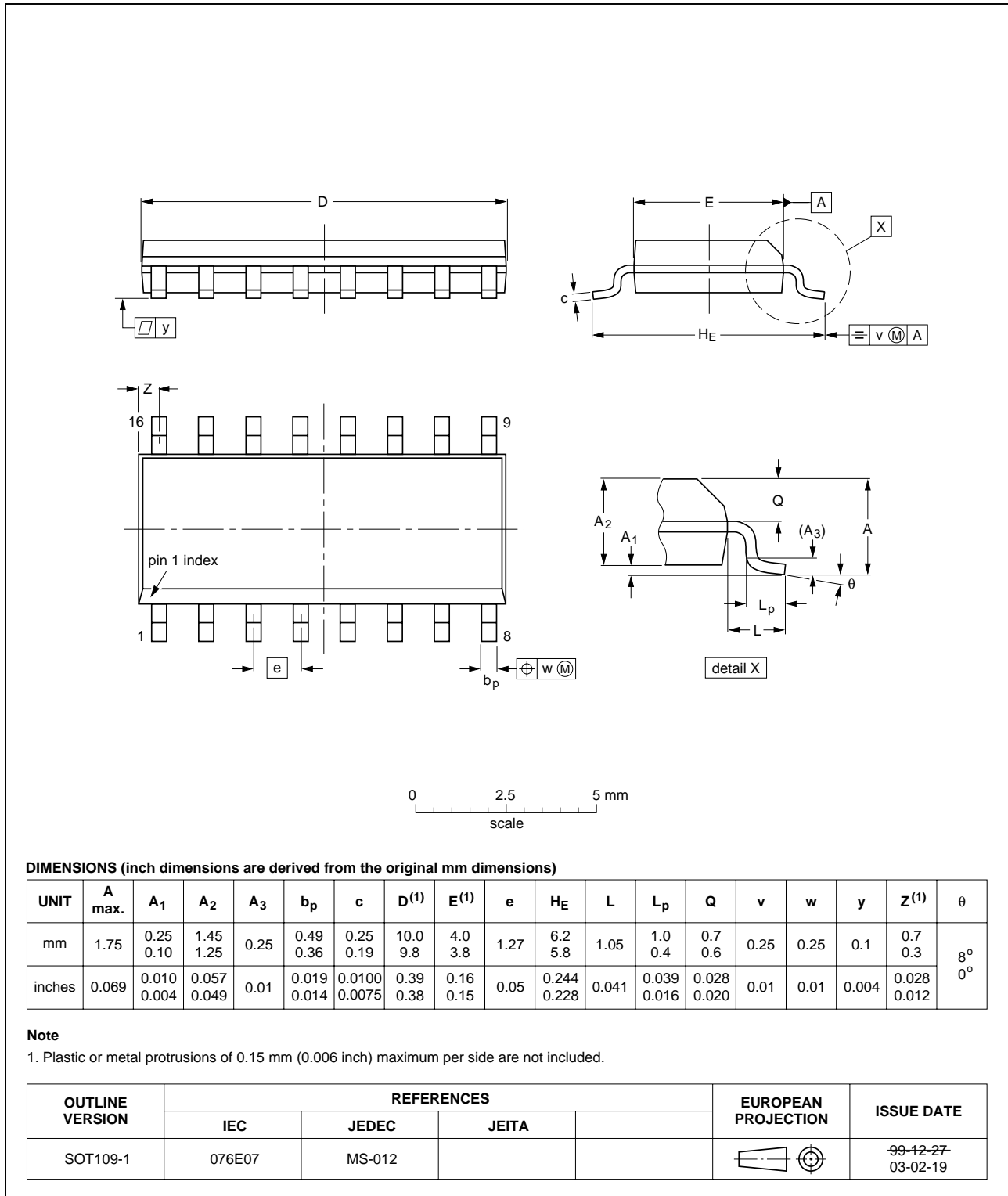


Fig 8. SO16 package outline (SOT109-1).

14. Soldering

14.1 Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *Data Handbook IC26; Integrated Circuit Packages* (document order number 9398 652 90011).

There is no soldering method that is ideal for all IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended. In these situations reflow soldering is recommended.

14.2 Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 270 °C depending on solder paste material. The top-surface temperature of the packages should preferably be kept:

- below 225 °C (SnPb process) or below 245 °C (Pb-free process)
 - for all BGA, HTSSON..T and SSOP..T packages
 - for packages with a thickness ≥ 2.5 mm
 - for packages with a thickness < 2.5 mm and a volume ≥ 350 mm³ so called thick/large packages.
- below 240 °C (SnPb process) or below 260 °C (Pb-free process) for packages with a thickness < 2.5 mm and a volume < 350 mm³ so called small/thin packages.

Moisture sensitivity precautions, as indicated on packing, must be respected at all times.

14.3 Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.

- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time of the leads in the wave ranges from 3 to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

14.4 Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

14.5 Package related soldering information

Table 9: Suitability of surface mount IC packages for wave and reflow soldering methods

Package ^[1]	Soldering method	
	Wave	Reflow ^[2]
BGA, HTSSON..T ^[3] , LBGA, LFBGA, SQFP, SSOP..T ^[3] , TFBGA, USON, VFBGA	not suitable	suitable
DHVQFN, HBCC, HBGA, HLQFP, HSO, HSOP, HSQFP, HSSON, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable ^[4]	suitable
PLCC ^[5] , SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended ^{[5][6]}	suitable
SSOP, TSSOP, VSO, VSSOP	not recommended ^[7]	suitable
CWQCCN..L ^[8] , PMFP ^[9] , WQCCN..L ^[8]	not suitable	not suitable

[1] For more detailed information on the BGA packages refer to the *(LF)BGA Application Note* (AN01026); order a copy from your Philips Semiconductors sales office.

[2] All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods*.

- [3] These transparent plastic packages are extremely sensitive to reflow soldering conditions and must on no account be processed through more than one soldering cycle or subjected to infrared reflow soldering with peak temperature exceeding $217\text{ }^{\circ}\text{C} \pm 10\text{ }^{\circ}\text{C}$ measured in the atmosphere of the reflow oven. The package body peak temperature must be kept as low as possible.
- [4] These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
- [5] If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- [6] Wave soldering is suitable for LQFP, QFP and TQFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- [7] Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.
- [8] Image sensor packages in principle should not be soldered. They are mounted in sockets or delivered pre-mounted on flex foil. However, the image sensor package can be mounted by the client on a flex foil by using a hot bar soldering process. The appropriate soldering profile can be provided on request.
- [9] Hot bar soldering or manual soldering is suitable for PMFP packages.

15. Revision history

Table 10: Revision history

Rev	Date	CPCN	Description
01	20040107	-	Product data (9397 750 08341). ECN 853-2443 A14996 dated 15 December 2003.

16. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2][3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

17. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

18. Disclaimers

Life support — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes in the products - including circuits, standard cells, and/or software - described or contained herein in order to improve design and/or performance. When the product is in full production (status 'Production'), relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no licence or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Contact information

For additional information, please visit <http://www.semiconductors.philips.com>.

For sales office addresses, send e-mail to: sales.addresses@www.semiconductors.philips.com.

Fax: +31 40 27 24825

Contents

1	Description	1
2	Features	1
3	Applications	1
4	Pinning information	2
4.1	Pinning	2
4.2	Pin description	2
5	Ordering information	3
6	Functional diagram division	3
7	Functional description	3
7.1	Function table	3
8	Limiting values	4
9	Recommended operating conditions	4
10	Static characteristics	5
11	Dynamic characteristics	6
12	Test figures	7
13	Package outline	10
14	Soldering	12
14.1	Introduction to soldering surface mount packages	12
14.2	Reflow soldering	12
14.3	Wave soldering	12
14.4	Manual soldering	13
14.5	Package related soldering information	13
15	Revision history	14
16	Data sheet status	15
17	Definitions	15
18	Disclaimers	15

© Koninklijke Philips Electronics N.V. 2004.
Printed in the U.S.A.

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Date of release: 07 January 2004

Document order number: 9397 750 08341



PHILIPS

Let's make things better.